



Microsectional Analysis

Quality Analysis - Evaluation - Advice

Microtek Laboratories has over 25-years of experience performing PCB and PCA evaluations. Microtek's personnel are leaders in the microelectronics industry and have established the industry standard for consistent high-quality Microsectional Analysis and test reports.

Microsectional Analysis remains the most widely accepted means for analyzing the PCB plated through-hole integrity. A PCB is a combination of different types of materials such as glass, aramid fibers, kapton, copper, acrylic adhesive, epoxy, polyimide, Teflon, solder, etc. Each of these materials has a different relative hardness and, coupled with that of the mounting media (epoxy, acrylic, etc.), makes the PCB microsection one of the most difficult to perform.

This process is further complicated by the fact that it is essential to complete microsectional preparation in an area within 10% of the center of the plated-through hole. Using the latest technology, Microtek's expert staff utilizes an automated coupon extraction station with a precision router-cutter (milling tool) for drilling two positioning holes and extracting the test coupons. Microtek can accurately microsection high-aspect ratio PCB's including blind and buried vias down to 0.001", SMT devices and solder joints. Whether you require regular conformance Microsectional Analysis, vendor qualification, or lot verification, Microtek has the experience and knowledge base to provide you with the highest quality and fastest turnaround available.

Microtek Laboratories is the electronics industry leader with over 25-years of experience in microsectional preparation and analysis. Specializing in PCB testing, Microtek is an approved DSCC facility and a registered ISO-9001:2000 firm. In addition to your in-house and customer specifications, Microtek can perform Microsectional Analysis in accordance with the following Military and Commercial specifications:

- IPC-A-600 – Acceptability of Printed Boards
- IPC-A-610 – Acceptability of Electronic Assemblies
- IPC-6012 – Qualification and Performance for Rigid Printed Boards
- IPC-6013 - Qualification and Performance for Flexible Printed Boards
- IPC-6016 - Qualification and Performance for High Density Interconnect (HDI) on Layers or Boards
- IPC-6018 – Microwave End Product Board Inspection and Test
- IPC-TM-650 – Test Methods Manual
- MIL-PRF-55110 - Performance Specification – General Specification for Printed Wiring Board, Rigid
- MIL-PRF-31032 - Performance Specification - General Specification for Printed Circuit Board/Printed Wiring
- MIL-P-50884 - General Specification for Printed-Wiring, Flexible and Rigid-Flex